

SF33 NO CLEAN REWORK FLUX

This product is a flux thinner and rework flux of the RMA type, i.e. mildly activated wood rosin. This material has been specifically formulated for use in rework applications and to thin SC3300 & SC3600 series no-clean solder pastes. This flux meets applicable military specifications. Leaves a hard clear residue that needs no solvent cleaning.

Typical Properties:

SIR: IPC-TM-650	>1X10 ⁹
Electromigration: Bellcore TR-NWT-000078	Pass
Halide: Per IPC-TM-650	Halide free
Flux corrosion: Per IPC-TM-650	Pass
Copper mirror: Per IPC-TM-650	Pass
Flux classification:	LO
Color:	Pale yellow
Consistency:	Low viscosity paste, free of nodules or lumps
Viscosity:	200-250 poise
Melting Point:	approx. 75°C
Tack Time:	Will remain tacky for 48 hours
Wetting Ability:	Will wet oxidized silver-palladium and clean copper
Shelf Life:	6 Months @ 25°C.
Storage:	Room temperature in tightly closed jars. Refrigeration may cause nodules to form. If any separation occurs during shipment, stir well prior to use to homogenize.

Note: The information contained in this data sheet is based on typical properties for the product. Actual shipment specifications for the product may vary. Please contact Heraeus for the product's shipment specifications.

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